



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



Technical specification:

Technische Daten:

Working voltage/ Betriebsspannung:	125 V AC
Insulation resistance/ Isolationswiderstand:	$\geq 5 \text{ G}\Omega$
Dielectric withstanding voltage/ Spannungsfestigkeit:	1000 V, 50 Hz, 1 min.
Temperature range/ Temperaturbereich:	-55 °C ... +125 °C
Current rating/ Strombelastbarkeit:	7,5 A (UL) / 5 A (CSA, VDE)
Mating cycles/ Steckzyklen:	Quality class 1 = 500 Gütestufe 1 Quality class 2 = 200 Gütestufe 2 Quality class 3 = 50 Gütestufe 3

Materials/

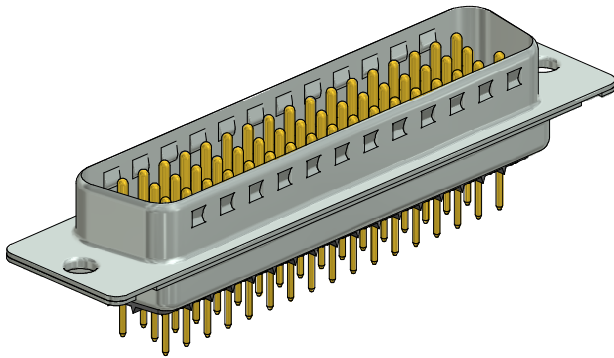
Werkstoffe:

Contact/ Kontakt:	Cu alloy, Au over Ni
Insulator/ Isolierkörper:	PBT GF UL 94 V-0, black/schwarz
Shell/ Gehäuse:	Steel, Sn over Ni



Installation specification/

Montagedaten:

PCB-Hole drillings/ Leiterplattenbohrbild:	see sheet 2/ siehe Seite 2
---	-------------------------------

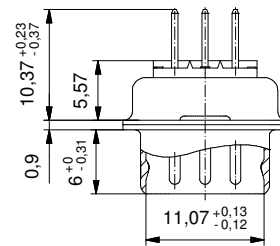
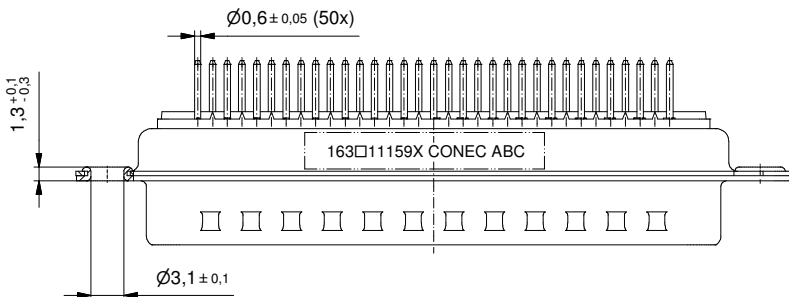
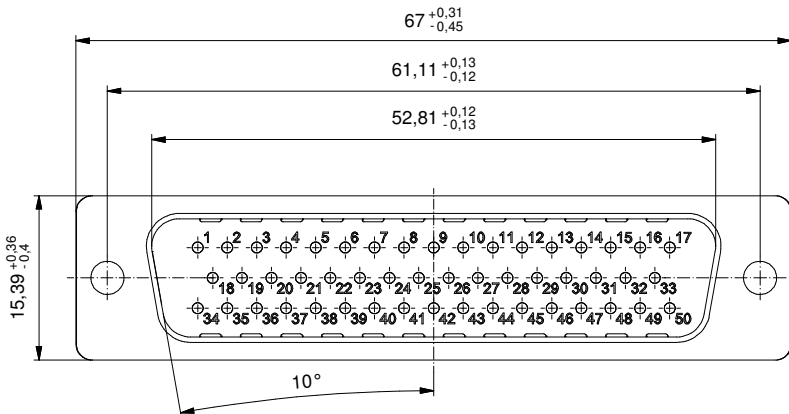
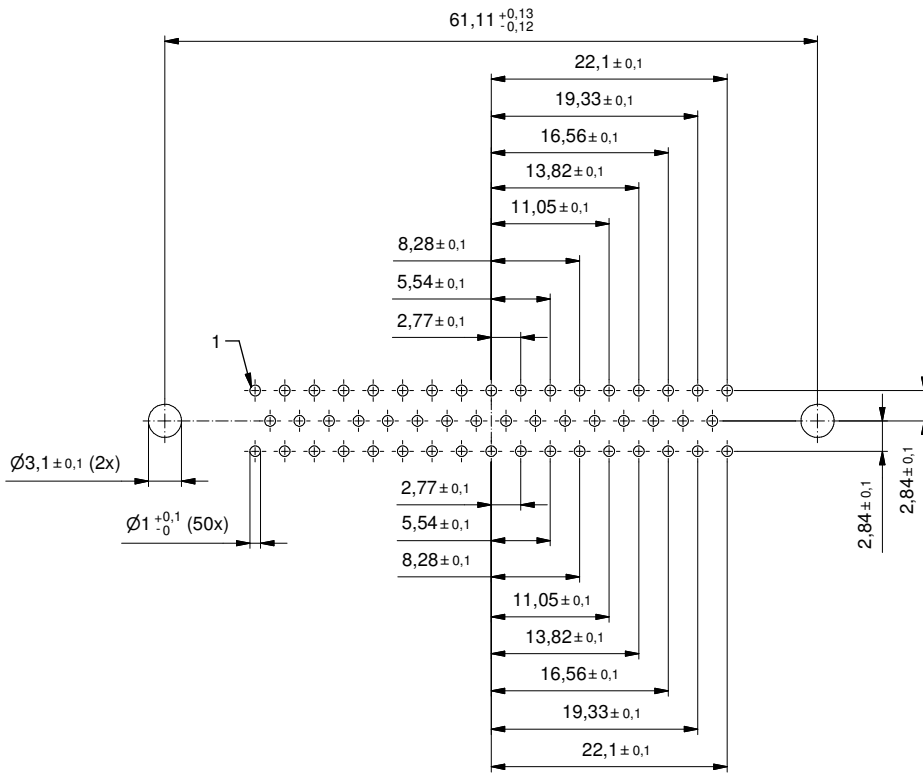


(b)

Part no. / Part Marked/ Art.-Nr. / Bedruckung:	Contact plating/ Kontakt Veredelung:		
163A11159X	Gold Flash over Nickel Gold über Nickel		
163B11159X	20 µm Hard Gold over min. 50 µm Nickel 20 µm Gold über min. 50 µm Nickel		
163C11159X	30 µm Hard Gold over min. 50 µm Nickel 30 µm Gold über min. 50 µm Nickel		
 dim. in mm	D-SUB Male 50pol. D-SUB Stiftleiste 50pos.		
drawn/ gez.	Date/Datum	Name	
appd./ gepr.	10.08.16	Henneboel	
	10.08.16	Lehmenkühler	
Index: Ind. b Ä6267 10.08.16 K.H.	scale/Maßstab:	dwg no / Z.-nr.:	DIN- A3
Status: InBearbeitung	2:1	16K1A2345	1 / 2
RoHS & REACH compliant/konform			

The reproduction, distribution and utilization of this document as well as the communication of its contents to others without express authorization is prohibited. Offenders will be held liable for the payment of damages. Wir bitten Sie, die Weitergabe, Verbreitung und Nutzung dieses Dokuments, insbesondere die Weitergabe an Dritte, ohne unsere schriftliche Genehmigung zu unterlassen. Zuwiderhandlungen werden strafrechtlich verfolgt.

PCB hole drillings
(PCB top side) /
Leiterplattenbohrbild
(Leiterplatten Oberseite)



		dim. in mm		D-SUB Male 50pol.	
		Date/Datum	Name	D-SUB Stiftleiste 50pos.	
drawn/gez.	10.08.16	Henneboel			
appd./gepr.	10.08.16	Lehmenkühler			
Index:	Ind. b Ä6267 10.08.16 K.H.	scale/Maßstab:	2:1	dwg no / Z.-nr.:	16K1A2345
Status:	InBearbeitung			DIN-	A3
RoHS & REACH compliant/konform					2 / 2

The reproduction, distribution and utilization of this document as well as the communication of its contents to third parties without express authorization is prohibited. Offenders will be held liable for the payment of damages. We hereby reserve the right to withdraw from the liability for damages.